

DOCUMENT TYPE: PLP

DOCUMENT ID #: 90-100046

REVISION: B-000

DOCUMENT TITLE: PACKAGE LAND PATTERN, [T1633Y+4C] TQFN-

EFFECTIVE DATE: 08/14/2023

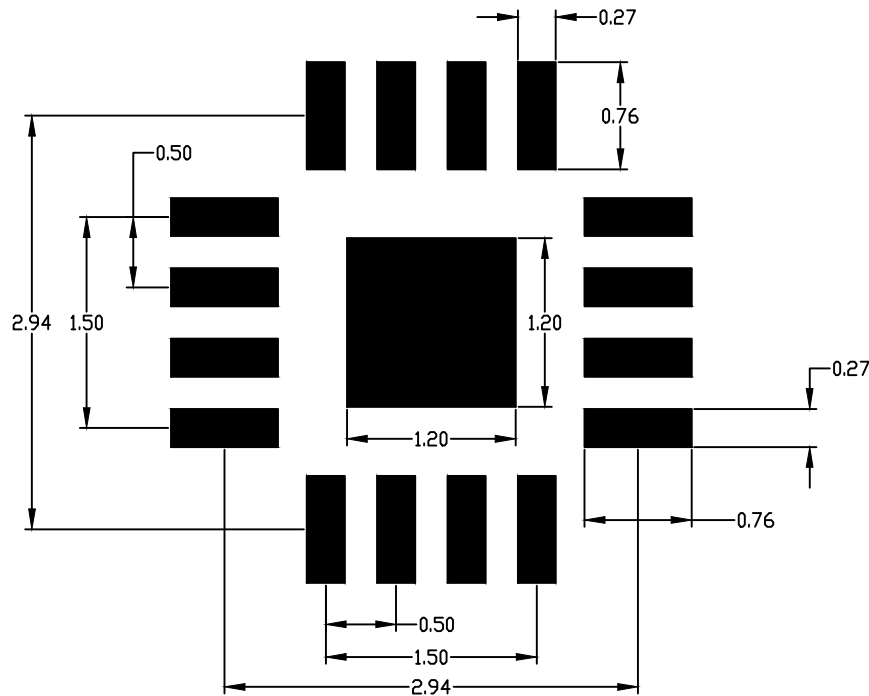
EXPIRATION DATE:

CHANGE NUMBER: 1193475

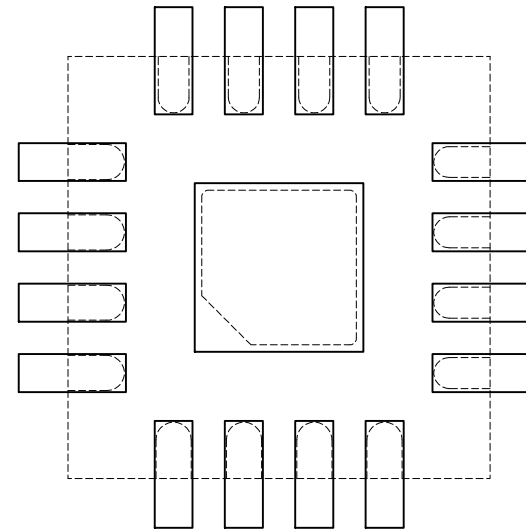
ORIGINATOR: Bernard Go

REASON FOR CHANGE:
Improved corner pins creepage clearance.

RECOMMENDED LAND PATTERN



PACKAGE OVERLAY



NOTES:

1. REFERENCE PKG. OUTLINE: 21-100108.
2. LAND PATTERN COMPLIES TO: IPC7351A.
3. TOLERANCE: +/- 0.02 MM.
4. ALL DIMENSIONS APPLY TO PbFREE (+) PKG. CODE ONLY.
5. ALL DIMENSIONS IN MM.

—DRAWING NOT TO SCALE—



This document (including dimensions, notes & specs) is a recommendation based on typical circuit board manufacturing parameters. Since land pattern design depends on many factors unknown to Analog Devices Inc. (eg. user's board manufacturing specs), user must determine suitability for use. This document is subject to change without notice. Contact technical support at <http://www.maxim-ic.com/support> for further questions.

TITLE: PACKAGE LAND PATTERN, [T1633Y+4C] TQFN-CU, SIDE-WETTABLE			
APPROVAL CHUCK XIA	DOCUMENT CONTROL NO. 90-100046	REV. B	1/1

